Docket No.

198778US2DIV

IN RE APPLICATION OF: MINORU OOHIRA ET A

SERIAL NO: 09/695,311

FILED:

OCTOBER 25, 2000

FOR:

SEMICONDUCTOR DEVICE HAVING PADS . . . MOTHER BOARD (AS AMENDED)

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Transmitted herewith is an amendment in the above-identified application.

No additional fee is required

Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.

Additional documents filed herewith:

Marked-up Copy of Claims

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS	RATE	CALCULATIONS
TOTAL	7	MINUS	20	0	× \$18 =	\$0.00
INDEPENDENT	2	MINUS	3	0	× \$84 =	\$0.00
		□ MULTIPLE DEPENDENT CLAIMS + \$280			+ \$280 =	\$0.00
			TOTAL OF A	BOVE CALCU	JLATIONS	\$0.00
□ Reduction by 50% for filing by Small Entity				\$0.00		
		□ Recore	dation of Assignment	:	+ \$40 =	\$0.00
					TOTAL	\$0.00

A check in the amount of

is attached.

- Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

Gregory J. Maier

Registration No. 25,599

Robert C. Mattson

Registration No. 42,850

GJM:RCM:djn

I:\atty\RCM\Prosecution\0057\198778.amdcvr.wpd

Tel. (703) 413-3000

Fax. (703) 413-2220

(OSMMN 10/00)

6/28/2

#10/Amd#13 DKnig 5/28/02

198778US2DIV

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

:

MINORU OOHIRA ET AL

EXAMINER: JONES, J.

SERIAL NO: 09/695,311

:

FILED: OCTOBER 25, 2000

GROUP ART UNIT: 2812



Bi

OR: SEMICONDUCTOR DEVICE
HAVING PADS FOR CONNECTING
A SEMICONDUCTING ELEMENT
TO A MOTHER BOARD (AS
AMENDED)

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

In response to the Office Action mailed December 5, 2001, please amend the aboveidentified patent application as follows:

IN THE CLAIMS

Please rewrite Claims 8-14 as follows:

8. (Amended) A method for producing discrete semiconductor devices, comprising the steps of:

forming a plurality of sets of die bond pads and wire bond pads by fastening electrically conductive metal sheets at specified positions on the back of an insulating sheet and making apertures in the insulating sheet on the metal sheets,